

1998

Foundation of the Japan Institute of Electronics Packaging

~ Packaging ~

The Japan Institute of Electronics Packaging (JEIP) was born in April 1998 by the merger of “Japan Association of Printed Circuits” and “Association of Hybrid Microelectronics Association of Japan”.

There was a request to Hajime Murakami to contribute a paper for the first issue of the journal of the institute with the theme of “Semiconductor Package Mounting Technology and Future Trends”, where the trend of package outline evolution was explained, such as pitch narrowing of array ball connection technology in surface mount technology (SMT), with the focus to QFP and BGA.

In the July 2009 issue, a paper was posted on the prediction of package warpage behavior by viscoelastic analysis for a package for high-speed signal transmission DRAM promoted by RAMBUS, where the stress measurement method was applied for small and high density packages. The paper was awarded the best paper award of this year.

